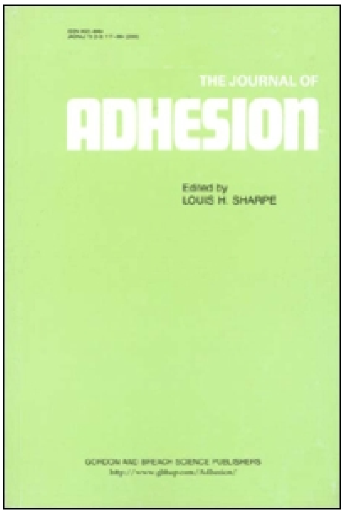

The Journal of Adhesion

Publication details, including instructions for authors and subscription information:
http://www.informaworld.com/smpp/title~content=t713453635

Calendar of Events

To cite this Article (2005) 'Calendar of Events', The Journal of Adhesion, 81: 9, 989 — 997
To link to this Article: DOI: 10.1080/00218460500292689
URL: http://dx.doi.org/10.1080/00218460500292689

The Journal of Adhesion, 81:989–997, 2005
Copyright © Taylor & Francis Inc.
ISSN: 0021-8464 print/1545-5823 online
DOI: 10.1080/00218460500292689

Taylor & Francis
Taylor & Francis Group

CALENDAR OF EVENTS

2005

August 13–16, 2005, Call for Papers for "Seeing at the NanoScale III", International Science Conference, University of California, Santa Barbara, USA, sponsored by California NanoSystems Institute (CNSI) and Veeco Instruments.

Masakazu Aono, National Institute for Materials Science (NIMS), Japan, is the keynote speaker.

Technical sessions are as follows:

SESSION 1: *Title*: Visualization I: Biomolecules and Biological Processes; *Focus*: Techniques to image cells, proteins, lipids, and tissue samples; *Invited Speaker*: Toshio Ando – Kanazawa University, Japan

SESSION 2: *Title*: Nanomechanical & Local Property Measurements; *Focus*: Methods to measure static and dynamic nanoscale mechanical and tribological properties, including Nanoindenting, scratching and NanoDMA. The session will also concentrate on molecular models and the understanding of fundamental properties in relation to the above measurement modes; *Invited Speaker*: Vinayak Dravid – Northwestern University

SESSION 3: *Title*: Visualization II: Materials and Polymer Systems; *Focus*: Methods to image and manipulate, from single macromolecule and functional self-assemblies to complete materials systems; *Invited Speaker*: Jean-Pierre Aime – University of Bordeaux, France

SESSION 4: *Title*: Measurements of Electrical, Optical, Magnetic & Thermal Properties of Materials at the Nanoscale; *Focus*: Material characterization in nanometer and submicron scale with emphasis on electrical, optical, magnetic and thermal properties

SESSION 5: *Title*: Instrumentation: New Tools and Techniques for Nanoscience; *Focus*: Innovative & future developments of SPM tools and techniques, probes and sensors; *Invited Speaker*: Carlos Bustamante – University of California, Berkeley

Topics may cover a wide range of nanoscale imaging and modification applications and techniques. Contributed papers will be considered for either oral or poster presentation at the conference unless the authors specifically request the poster session. The deadline for abstracts submission is April 22, 2005 at 5:00 p.m. PST.

If you are interested in submitting an abstract, please see: www.veeco.com/nanoconference/call_for_papers.asp for detailed submission guidelines and session-specific information.

September 7–9, 2005, First Announcement and Call for Papers. Ninth International Conference on The Science and Technology of Adhesion and Adhesives, St. Catherine's College, University of Oxford, UK. Organized by IOM Communications Ltd. on behalf of The Institute of Materials, Minerals and Mining. Coordinated by The Society for Adhesion and Adhesives.

Authors who wish to make a presentation are requested to send an abstract of no more that 300 words (1 page), in English, by 31 December 2004, to: John Bishopp, Star Adhesion Limited, Star House, 40 Station Road, Waterbeach, Cambridge CB5 9HT, UK.

Abstracts may be sent by e-mail (preferred method) to: john.bishopp@btinternet.com as an attached Word or pdf document. Please ensure that you put "Adhesion '05 Abstract" in the subject box. All papers and presentations will be in English and a condition of acceptance will be that at least one author from each paper will pay to attend the conference and present the work.

The extended abstracts (4 pages maximum) of the accepted papers will be published in the "Proceedings of Adhesion '05" which will be available in "hard copy" and CD-ROM at the conference.

Important Dates:

31 December 2004. Final date for receipt of short abstracts (1 page)
February 2005. Notification of acceptance to authors
1 April 2005. Dispatch of provisional programme and registration document
30 June 2005. Final date for receipt of extended abstracts (max 4 pages including figures)
31 July 2005. Final date for registration at the special early rate.

Further Information: Lisa Bromley, Conferences & Events (C0504), IOM Communications Ltd., 1 Carleton House, London SW1Y 5DB, UK. Direct Tel.: +44 (0)20 7451 7303; Switchboard: +44 (0)20 7451 7300; Fax: +44 (0)20 7839 1702; E-mail: lisa.bromley@iom3.org, Website: www.iom3.org

John Bishopp, Star Adhesion Ltd., Star House, 40 Station Road, Waterbeach, Cambridge CB5 9HT, UK. Tel.: +44 (0) 1223 861338; Fax: +44 (0) 1223 864467; E-mail: john.bishopp@btinternet.com

September 11–14, 2005, Call for papers for the 4th ESIS TC4 International Conference on Fracture of Polymers, Composites and Adhesives, Les Diablerets, Switzerland. The Conference is being organized by Elsevier/ESIS TC4 Committee. Abstracts of 300 words (maximum) are invited for oral and poster presentations. They may be submitted on line at the website given below.

Important dates are:

Deadline for submission of abstracts: November 1, 2004
Decision on Abstracts: January 1, 2005
Submission of 1-page abstracts for abstracts book: June 1, 2005
Submission of full papers: 11 September 2005

For further information contact: Claire Norris, TC4 Conference Secretariat, 51 Kestrel Way, Wokingham, Berkshire RG41 3HA, UK. Tel.: +44 (0) 118 377 4696; Fax: +44 (0) 118 977 6680; E-mail: TC4-conference@elsevier.com, Website: www.tc4pca.elsevier.com

Oct 15–18, 2006, World Congress on Adhesion and Related Phenomena, WCARP-III Beijing, PR China

The 3rd World Congress on Adhesion and Related Phenomena, WCARP-III, is built upon a proven concept and continues the tradition of its two predecessors, in Germany 1998 and in the USA 2002, after its initiation in 1994, during an international meeting of the Japanese Adhesion Society. This quadrennial conference series provides a forum for researchers from around the globe to present papers on recent advances in the overall field of adhesion science and technology and related phenomena such as surface technologies, nano-technology, etc.

Plenary Presentations and Speakers

1. Prof. Dr. Masao Doi, University of Tokyo, Japan
   Rheology at Polymer Surface
2. Prof. Dr. David Dillard, Virginia Tech, USA
   Rate-Dependent Fracture of Adhesive Bonds
3. Dr. R.A.Chivers, Smith & Nephew Research Centre, UK
   Adhesion in the human body

Co-operating Organizations

The American Adhesion Society, USA
The Beijing Adhesion Society, China
The British Society for Adhesion and Adhesives, UK
The French Adhesion Society, France
The German DECHEMA, Germany
The Japanese Adhesion Society, Japan
The Korean Adhesion Society, Korea

TOURS: WCARP-III will offer a variety of tours to suit your needs.

For full information concerning the meeting and for instructions for the preparation of contributed papers, please visit WCARP-III's Web site: http://www.wcarp.cn

Short Course: Efficient Testing of Adhesives and Sealants

October 23–26, 2005, Virginia Tech – Blacksburg, Virginia, USA. The Macromolecules and Interfaces Institute at Virginia Tech presents a unique lecture-laboratory short course for anyone who wants to choose fewer/better/smarter tests to get the answers they need in adhesion science. The course is taught by Virginia Tech faculty.

This course will teach you to…

- Understand and select appropriate test methods to measure relevant properties
- Improve consistency through understanding and controlling surface, polymer, and test variables
- Take advantage of statistical procedures such as design of experiment (DOE) concepts to reduce the number of tests required
- Make use of combinatorial and parallel formulation techniques to speed product development
- Take advantage of accelerated characterization techniques to speed polymer and bond testing
- Interpret test results through *post mortem* analysis of failure surfaces and statistical tools

For more information, contact Tammy Jo Hiner at (540) 231-6824, fax (540) 231-3971, or e-mail at thiner@vt.edu. Register on-line at http://www.conted.vt.edu/reg/etas/

The Course is limited to 30 participants, so it would be wise to enroll as soon as possible.

November 2–4, 2005, Announcement and Call for Papers, "Wood Adhesives 2005", Holiday Inn on the Bay, San Diego, California, USA. This is the eighth in a series of symposia sponsored every 5 years by the USDA Forest Service, Forest Products Laboratory, designed to provide a comprehensive update of the science and technology of wood adhesives and bonded wood products. Information transfer during the 3-day symposium will take place via a workshop, technical and poster presentations, tabletop exhibits and a discussion forum on the following subject areas:

- Resin chemistry involving petroleum and biomass feedstocks
- Characterization of adhesive-wood interactions using new analytical techniques
- Durability of wood bonds
- Adhesive aspects of wood-based composites
- Performance of the adhesives in engineered wood products
- Current and future markets for wood adhesives and bonded wood products
- General and poster sessions

This symposium is sponsored by the USDA Forest Service, Forest Products Laboratory in cooperation with the Forest Products Society. As additional information on the program is developed, it will be available at: http://www.forestprod.org

For more information contact:

Forest Products Society
2801 Marshall Court, Madison, WI 53705-2295, USA.
Tel.: 608-231-1361, ext. 208; Fax: 608-231-2152;
E-mail: conferences@forestprod.org
Website: www.forestprod.org

Announcement and Call for Papers

The 29th Annual Meeting of the Adhesion Society will take place on February 19–22, 2006, at the Radisson Riverwalk Hotel, Jacksonville, Florida. The Particle Division of the Society wishes to determine participant interest in the subject of "Adhesion at the Nanoscale, and its Consequences". To that end, responses of interest, and potential papers, are being sought in the following areas:

Nanoscale adhesion measurement techniques;

Nanoparticle (nanoclusters, nanotubes, etc.,) adhesion, and its consequences;

Nanoparticle removal (during semiconductor manufacture, CMP processing, etc.);

Nanoparticle coalescence;

Bioparticle (bacteria, cells, viruses, etc.) adhesion, and its consequences.

Please send indications of interest, possible presentations and suggestions to:

Edward Sacher
Department of Engineering Physics
Ecole Polytechnique
P. O. Box 6079, Station Centre-Ville
Montréal, Québec H3C 3A7
Canada
Telephone: (514)340-4711, extension 4858
Fax: (514)340-3218
E-mail: edward.sacher@polymtl.ca

Notice of Meeting and Call for Papers

February 19–22, 2006, 29th Annual Meeting of The Adhesion Society, Inc., Radisson Riverwalk Hotel, Jacksonville, Florida, USA. A full program, focused on the application of adhesion science to the solution of technical, is planned.

Topics of Emphasis for the meeting are solicited in all areas of adhesion science and technology, with emphasis on:

- Surface Interactions
- Contact Mechanics
- Bioadhesion
- Particle Adhesion
- Pressure Sensitive Adhesion
- Structural Adhesives
- High Throughput Adhesion Testing
- Corrosion and Adhesion
- Adhesion of/to Patterned Surfaces
- Interfaces in Electronic Systems

A session on "Molecular Mechanisms of Polymer Adhesion and Fracture," which opens the meeting, will honor Professor Hugh Brown, who has been selected to receive the *Adhesion Society Award for Excellence in Adhesion Science, Sponsored by 3M.*

A Poster Session, which covers all topics related to adhesion science, will be an integral part of the meeting.

An Exhibition of equipment and literature relating to adhesion science will be held in conjunction with the Annual Meeting. For more information, contact The Adhesion Society Home Office, 540-231-7257 or <adhesoc@vt.edu>

A two-day Short Course on Adhesion will be held on February 19–22, 2006, just prior to the Annual Meeting.

Submission of Short Abstracts

Authors wishing to present a paper or a poster should submit short abstracts of 150–250 words, *ELECTRONICALLY*, to The Adhesion Society Home Office, <adhesoc@vt.edu>, by August 15, 2005.

If you wish to target your abstract for a particular session, so indicate on the abstract. **Please underline** the name of the presenting author and include contact information. Authors will be informed of the status of their papers by October 15, 2005.

Submission of Extended Abstracts

Authors of accepted papers will receive instruction for preparation of extended abstracts (maximum of three (3) pages). Extended abstracts must be submitted no later than **December 1, 2005**, for inclusion in the bound meeting proceedings.

Submission of the extended abstracts will be accepted *ELECTRONICALLY*, in Microsoft Word compatible format, at the Adhesion Society home office, <adhesoc@vt.edu>

The Website address is: http://www.adhesionsociety.org

The 2004 de Bruyne Medal of the Society of Adhesion and Adhesives will be awarded to Dr. William A. Lees, formerly of Permabond, at the major international conference on adhesion and adhesives [Adhesion 05], which is to be held at St. Catherine's College in Oxford, UK, on 7–9 September 2005. Dr. Lees will also deliver a paper entitled: *De Bruyne: Legend and Legacy*. There have been only three previous recipients of the Award: Dr. Stephanie Wellman of Permabond in 1996, Dr. Iain Webster of Smith and Nephew in 1999 and Dr. Michael Owen of Dow Corning in 2001.

The de Bruyne medal is named in honour of the founder of Aero Research Limited: Norman de Bruyne, FREng, FRS [1904−1997]. De Bruyne was a multi-disciplined scientist who had the ability and foresight to translate theoretical science into very practical, commercial applications. Three examples are: the development, in 1936, of the first structural composite [Gordon Aerolite©] for use in aircraft; in 1942 the invention of Redux©, a synthetic heat-curing adhesive for structural bonding and patenting, in 1938, the concept of metal honeycomb. All three concepts are still widely used in the aerospace industry. The medal is presented to an individual who displays these characteristics. It is an acknowledgment of the recipient's personal contribution to innovation in the field of adhesives.

Dr. Lees has had a distinguished 35-year career as Technical Director with Permabond. He made significant advances in very varied fields within the adhesion and adhesive disciplines as well as being responsible for establishing the entire *modus operandi* of the company which was to become Permabond. His achievements include: the development of chemical techniques for soil stabilisation in, for example, the construction of tunnels and dams; the development of a range of anaerobic adhesives which were manufactured by novel techniques and which ultimately led to the so-called toughened acrylic adhesives; the introduction of the first cyanoacrylate adhesives manufacture to the UK. Adhesive innovations by Dr. Lees and his team have significantly advanced the construction technologies of the automotive industry [the ECV3 the first all bonded aluminium car], civil engineering [gas pipe repair] and defence [Law 80 rocket launcher]. One of his enduring legacies, apart from his numerous papers and books, is the development of the expert system "PAL" used for guiding adhesive selection by the end-user.

The Medal Committee comprises members of the Society for Adhesion and Adhesives [SAA], TWI and Huntsman Advanced Materials [originally Aero Research Limited/Ciba]. The CEO of Huntsman Advanced Materials, Paul Hulme, is to present the award to Dr. Lees.

Nominations are now being sought for a de Bruyne medallist for 2006. An application form is to be found on the SAA Website: http://www.uksaa.org

For further information contact:

John Bishopp
Society for Adhesion and Adhesives
c/o Star Adhesion Limited
Star House, 40 Station Road, Waterbeach,
Cambridge, CB5 9HT, UK
Tel.: +44 1223 861338
E-mail: john.bishopp@btinternet.com

Forthcoming Book

Adhesion – Current Research and Applications

Edited by Wulff Possart,
Universität des Saarlandes,
Saarbrücken, Germany

Thirty-four international authors provide contributions based on their lectures at the 7th European Adhesion Conference EURADH 2004 in Freiburg, Germany in September 2004.

Presenting a comprehensive survey of the latest research and development in the area of adhesion, this book also describes key aspects of applications of adhesion and adhesives that are of importance in microtechnology, transportation, coatings, medicine, surface treatment and engineering. It is a multidisciplinary guide to research applications and advanced technologies of adhesion.

Table of Contents:

Adhesive Interphases and Fundamental Adhesion
Adhesion and Biology
Chemistry for Adhesives
Pretreatment and Surface Chemistry of Adherends
Mechanics and Non-Destructive Testing of Adhesive Joints
Ageing and Durability in Adhesive Joints
Advanced Adhesive Technology

Date of Publication: July 2005
600 pages with approx 250 figures
Wiley-VCH, Weinheim
ISBN 3-527-31263-3
Approx. price: €159.- / sFr235.-

For further information contact:

W. Possart
E-mail: w.possart@mx.uni-saarland.de